承 认 书

SPECIFICATION FOR APPROVAL

客 户 **Customer**	:	
客 户 批 号 **Customer Part No.**	:	
型 号 **Part No.**	:	K3030P15K0MZ001
制 作 人 **Prepared By**	:	日期 **Time: 2020/09/18**
审 核 **Checkedy**	:	日期 **Time: 2020/09/18**
客 户 回 签 **Customer Comfirmation**	:	日期 **Time:**

客户意见栏（ Customer’S Proposal）

☐ Approve 承认 （请于认可栏中签名） ☐ Disagree 不同意

Reason 原因:_____

版 本 （ Version): 1.3

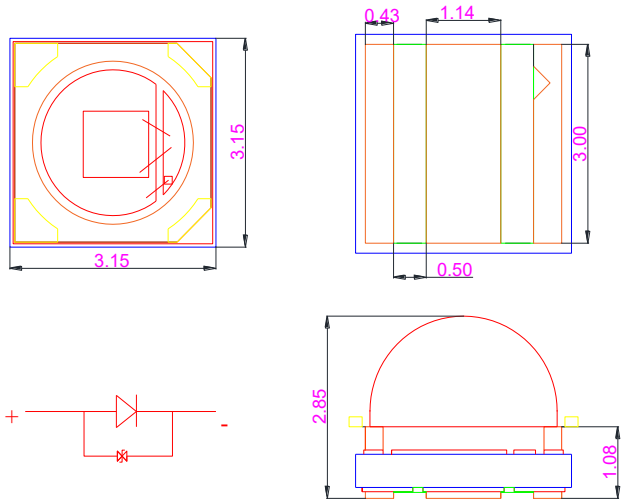
● Features:

1. Emitted Color: UV
2. Lens Appearance: Clean quartz lens
3. 3.15x3.15x2.85mm standard package.
4. Suitable for all SMT assembly methods.
5. Compatible with infrared and vapor phase reflow solder process.
6. Compatible with automatic placement equipment.
7. This product doesn't contain restriction Substance, comply ROHS standard.

● Applications:

1. UV Curing

●Package Dimensions:



NOTES:
1. All dimensions are in millimeters.
2. Tolerance is ±0.10mm unless otherwise specified.
3. Specifications are subject to change without notice.

● Part Numbering System:

K	3030	P1	5K	0	M	001
（1）	（2）	（3）	（4）	（5）	（6）	（7）

（1）K : Substrate code

（2）Package type: 3030

（3）LED Color：P1 means UVA segment

（4）Chip code

（5）0:CRI not required

（6）M:Type of Silicon

（7）001: Wavelength bin

● Absolute Maximum Ratings（Ta=25℃）

Item	Symbol	Value	Unit
Power Dissipation	PD	3	W
DC Forward Current	IF	700	mA
Single Chip Pulsed Forward Current	IFP	1000※	mA
Reverse Voltage	VR	5	V
Operating Temperature	Topr	-30～+80■	℃
Storage Temperature	Tstg	-40～+120	℃
Soldering Temperature	Tsol	260for5sec△	℃

※Duty 1/10， Pulse Width 0.1ms.
△ Soldering time max 10sec
■please refer to IF-Ta diagram of curves for the temperature during application

●Parameter

Parameter	Symbol	Value			Unit	Test condition
		Min.	Typ.	Max		
Forward Voltage	Vf	-	3.7	-	V	If=700mA
Reverse Current	Ir	-	-	10	μA	Vr=5V
Viewing angle	2θ1/2	-	60	-	Deg	If=700mA
Peak Wavelength	λp	365	-	370	nm	If=700mA
Luminous Power	Po		900	-	mw	If=700mA

● Typical Electro-Optical Characteristics Curves

Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

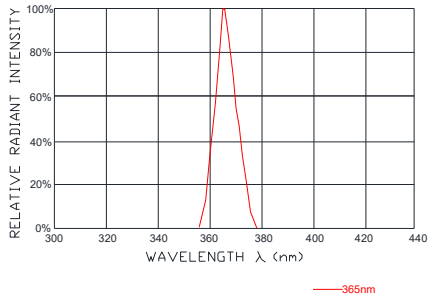


Fig.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

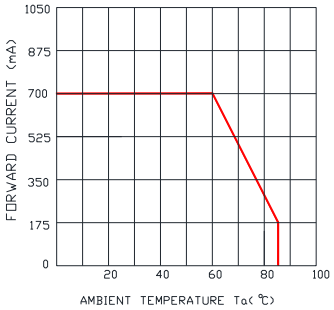


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

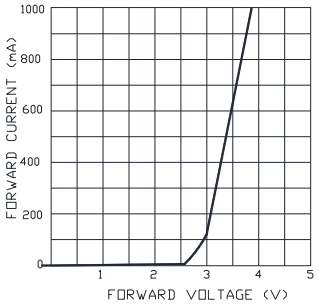


Fig.4 RELATIVE LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

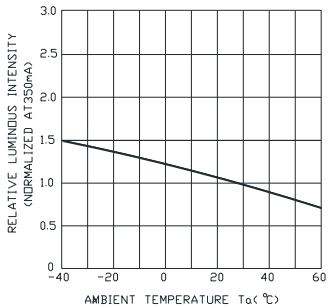


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

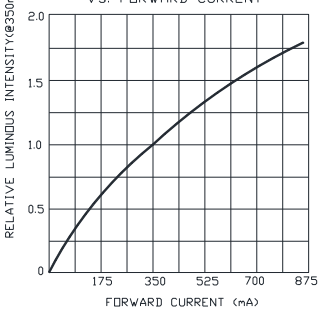
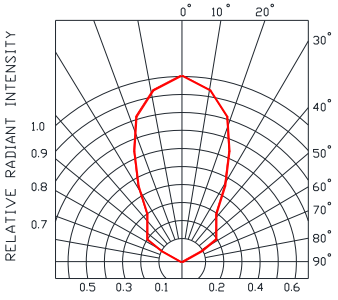


Fig.6 RADIATION DIAGRAM



●Test items and results of reliability

Type	Test Item	Test Conditions	Note	Number of Damaged
Operation Sequence	Life Test	T_a=25℃ I_F=700mA	1000 hrs	0/22
	High Humidity Heat Life Test	85℃ RH=85% I_F=700mA	500 hrs	0/22
Environmental Sequence	Temperature Cycle	-45℃ 30min ↑↓20 min 105℃ 30min	100 cycle	0/22
	Thermal Shock	-10℃ 15min ↑↓5sec 100℃ 15min	100 cycle	0/22
	High Humidity Heat Cycle	30℃⇔ 65℃ 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	T_a=100℃	1000 hrs	0/22
	Humidity Heat Storage	T_a=85℃ RH=85%	1000 hrs	0/22
	Low Temperature Storage	T_a=-40℃	1000 hrs	0/22

●Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	V_F (V)	I_F=700mA	Over U^1x1.2
Reverse current	I_R (uA)	V_R=5V	Over U^1x2
Luminous intensity	Iv (mcd)	I_F=700mA	Below S^1X0.5

Note: 1. U means the upper limit of specified characteristics. S means initial value.

2. After each test, remove test pieces, wait for 2 hours and test pieces have returned to ambient temperature, then take next measurement.

● Soldering :

1. Manual Soldering

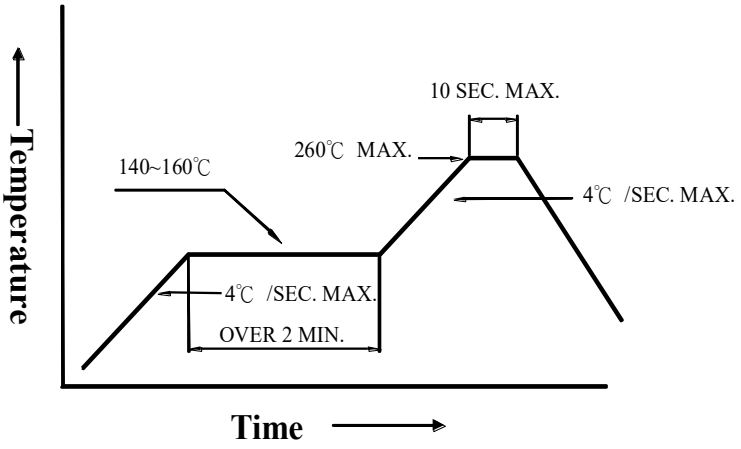
The temperature of the iron tip should not be higher than 350℃and Soldering time to be within 3 seconds per solder-pad.

2. Reflow Soldering

Preheating : 140℃~160℃±5℃,within 2 minutes.

Operation heating : 260℃(Max.) within 10 seconds.(Max)

Gradual Cooling (Avoid quenching).



● Storage:

In order to avoid the absorption of moisture, it is recommended to solder LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

(1) Temperature : 5℃-30℃(41℉)Humidity : RH 60％Max.

(2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:

a. Completed within 168 hours.

b. Stored at less than 30% RH.

(3) Devices require baking before mounting, if:

(2) a or (2) b is not met.

(4) If baking is required, devices must be baked under below conditions:

48 hours at 60℃±3℃.

● Package and Label of Products:

（1）Package: Products are packed in one bag of 500 pcs (one taping reel) and a label is attached to each bag.

（2）Label:

Part No. : XXXXXXXXX
Type No. : E-XXXX-XX-XX-XX-XXX
VF(700mA) : XX-XX
IV(700mA) : XXXX-XXXX
CCT(700mA): XXXX-XXXX
Q'TY : XXXXPCS
Lot No. : X-XXX-XX-X

● **Tapping and packaging specifications (Units: mm)**